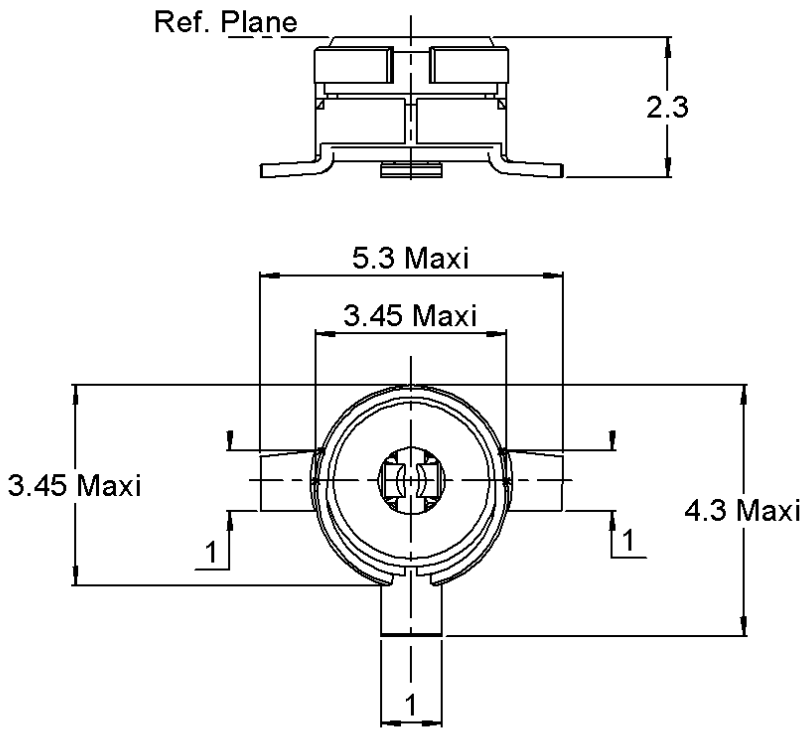
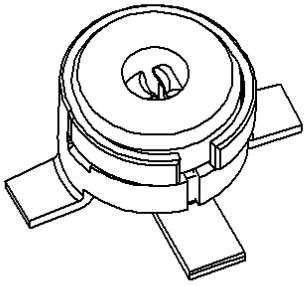
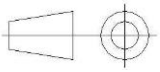
| PAGE **1/5** | ISSUE **03-02-17B** | SERIES **MMS** | PART NUMBER **R209408012** |
|---|---|---|---|



Scale: 1/1

All dimensions are in mm.



| COMPONENTS | MATERIALS | PLATING (µm) |
|---|---|---|
| Body | **PHOSPHOR BRONZE** | **GOLD 0.2 OVER NICKEL 2** |
| Center contact | **BERYLLIUM COPPER** | **GOLD 0.2 OVER TIN NICKEL 2** |
| Outer contact | | |
| Insulator | **PTFE** | |
| Gasket | **-** | |
| Others parts | **-** | **-** |
| - | **-** | **-** |
| - | **-** | **-** |

## PACKAGING

| Standard | Unit | Other |
|---|---|---|
| **100** | **Contact us** | **Contact us** |

## ELECTRICAL CHARACTERISTICS

| | | | |
|---|---|---|---|
| Impedance | | **50** | Ω |
| Frequency | | **0-6** | GHz |
| VSWR | * + | **0,0000** | x F(GHz) Maxi |
| Insertion loss | | ** | √F(GHz) dB Maxi |
| RF leakage | - ( | **NA** | - F(GHz)) dB Maxi |
| Voltage rating | | **50** | Veff Maxi |
| Dielectric withstanding voltage | | **250** | Veff mini |
| Insulation resistance | | **500** | MΩ mini |

## MECHANICAL CHARACTERISTICS

| | | |
|---|---|---|
| Center contact retention | | |
| Axial force – Mating End | **NA** | N mini |
| Axial force – Opposite end | **NA** | N mini |
| Torque | **NA** | N.cm mini |
| Recommended torque | | |
| Mating | **NA** | N.cm |
| Panel nut | **NA** | N.cm |
| Mating life | **50** | Cycles mini |
| Weight | **0,0590** | g |

## ENVIRONMENTAL

| | | |
|---|---|---|
| Operating temperature | **-40/+125** | °C |
| Hermetic seal | **NA** | Atm.cm3/s |
| Panel leakage | **NA** | |

## SPECIFICATION

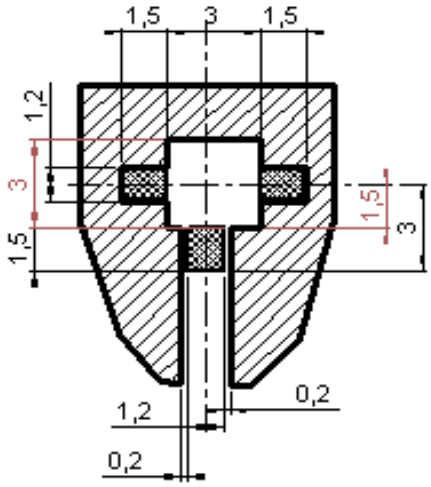
## OTHER CHARACTERISTICS

Assembly instruction:

Others:
***1.2 à 2GHz/Avg 1,07 **Max 0.07/Avg 0.06**

## *MMS SERIES – INFORMATION*

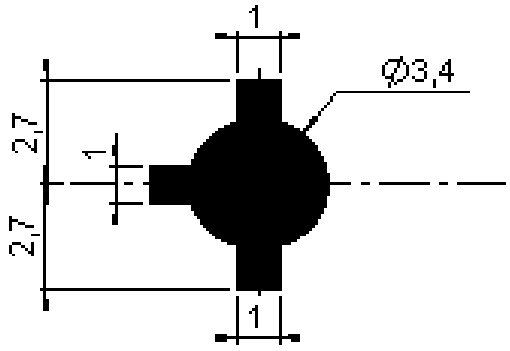
Coplanar line : Ground and signal are on the same side . Thicknass of PCB : 1mm
The material of PCB is glass-epoxy composite. (Er = 4.8 )
The sold er resist should be printed except for the land pattern on the PCB.



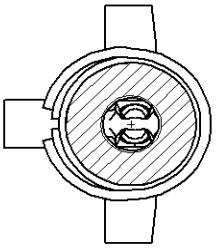

Pattern

Land for solder paste

## *SHADOW OF MMS RECEPTACLE*
### FOR VIDEO CAMERA




## *ASPIRATION AREA*



ASPIRATION AREA

# SOLDER PROCEDURE

1. Deposit solder paste 'SnAg4Cu0.5' on mounting zone by screen printing application. We recommend a low residue flux. We advise a thickness of 150 micromm ( 5.850 microinch ). Verify that the edges of the zone are clean.

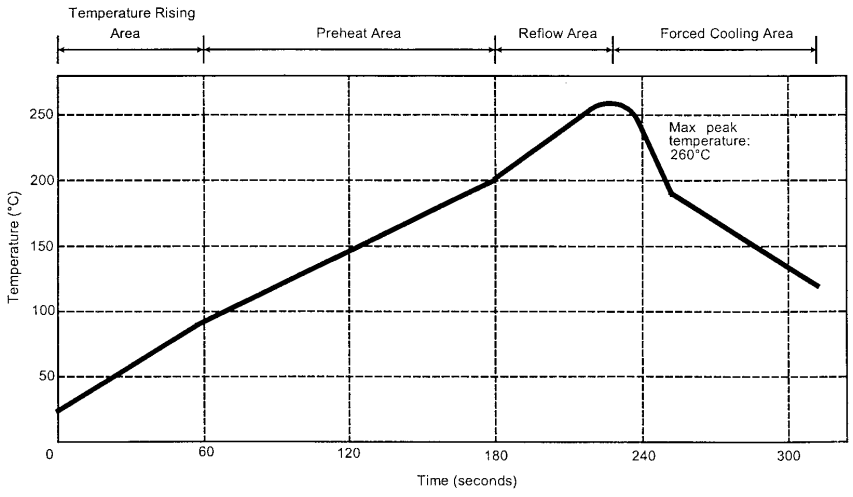
2. Placement of the receptacle on the mounting zone with an automatic machine of 'pick and place' type.

3. Soldering by infra-red reflow.

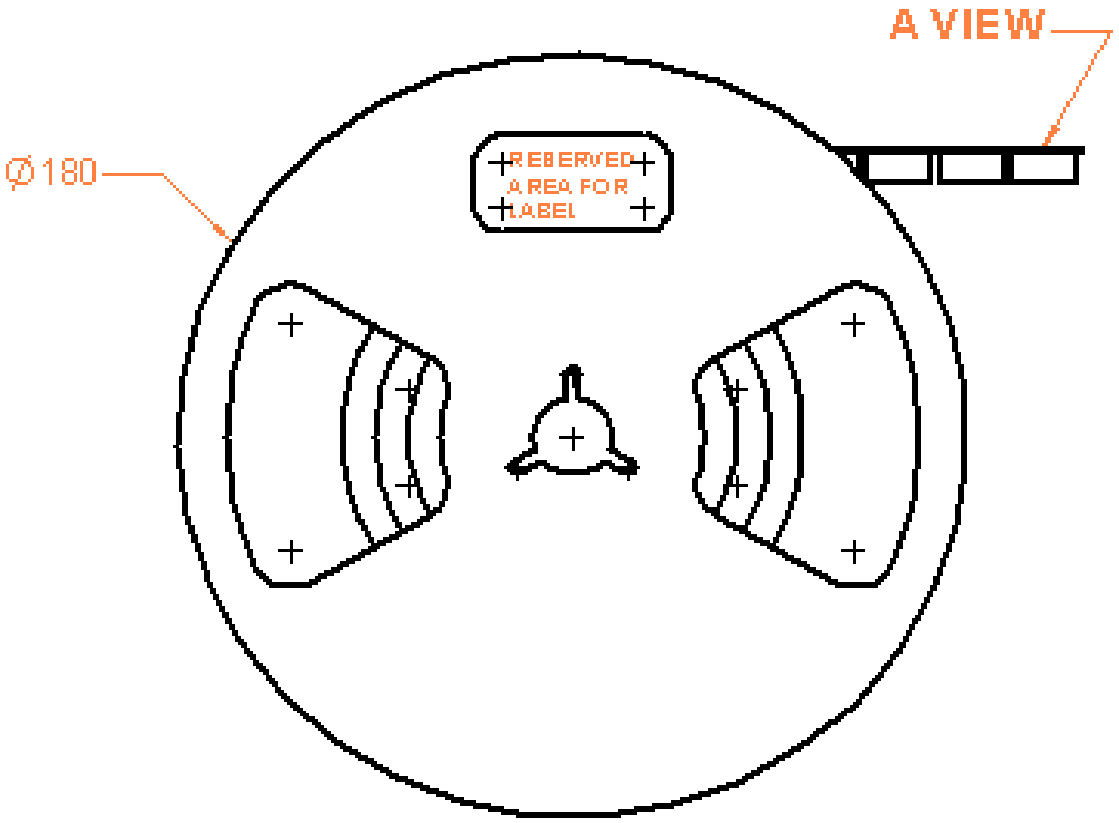
4. Cleaning of printed circuit boards.

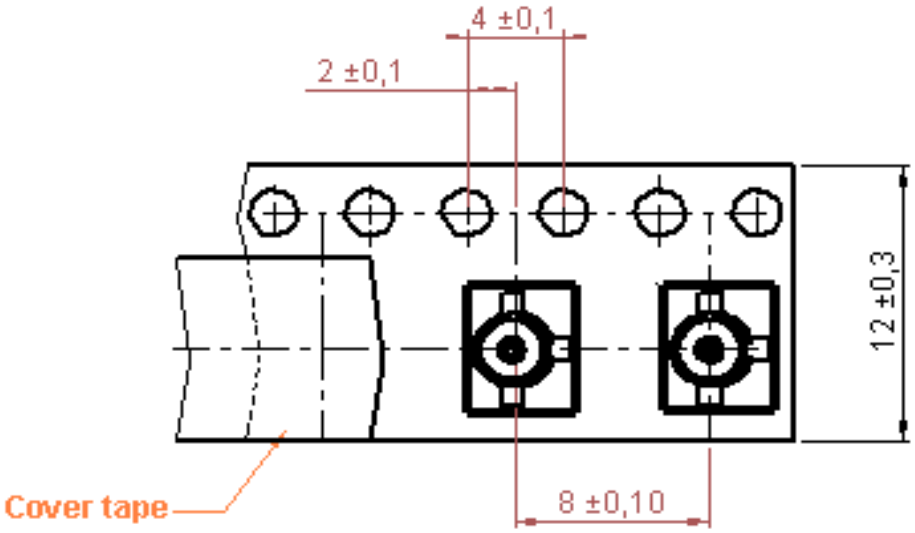
5. Checking of solder joints and position of the component by visual inspection.

## *TEMPERATURE PROFILE*




| Parameter | Value | Unit |
|---|---|---|
| Temperature rising Area | 1 - 4 | °C/sec |
| Max Peak Temperature | 260 | °C |
| Max dwell time @260°C | 10 | sec |
| Min dwell time @235°C | 20 | sec |
| Max dwell time @235°C | 60 | sec |
| Temperature drop in cooling Area | -1 to - 4 | °C/sec |
| Max dwell time above 100°C | 420 | sec |




A VIEW ( scale : 4 )